Silecs Joins 11th Electronic Packaging Research Consortium

Singapore, 15 June 2011 The Institute of Microelectronics (IME), a research institute of the Agency for Science, Technology and Research (A*STAR) has launched its 11th Electronic Packaging Research Consortium (EPRC11) to address various technology challenges in advanced packaging technology in semiconductor in enabling smaller and smarter devices. Since IME initiated the first EPRC in 1996, this resource and cost-sharing platform has injected invaluable R&D capabilities into the operations of many local enterprises and multi-national companies in the electronic packaging industry and its value chain.

Professor Dim-Lee Kwong, IME's Executive Director said, "EPRC started 15 years ago and we have gone through 10 cycles of projects with our members, offering high quality R&D expertise in IC packaging. The success of this consortium since 1996 is a testimony to the significance of this platform in offering companies engaged in pre-competitive R&D and looking to develop new capabilities to stay ahead of their competitors… IME is committed to engage packaging solutions as we continue to see smaller and smarter products in the market."

Mr. Teo Kok Whee, CEO of Silecs International commented: "Silecs, being an acknowledged pioneer in advanced electronic materials, is enabling customers' processes with our nano-engineered polymers. We have recently announced our new round of funding to accelerate our technology development to address the fast emerging needs of advanced packaging and several opto-electronic applications. Today, we have joined the leading advanced packaging solution providers to develop the next generation packaging platform."

The two projects that Silecs is collaborating with IME and consortium members are: a) Multiple Chip Embedded Wafer Level Packaging to address the re-construction process challenges and develop validated numerical models; b) the Fine Pitch Flip Chip with Cu Pillar project aims to develop a low-stress Cu pillar flip-chip technology on Cu low-k chips.

EPRC11 consists of 23 company members spanning the whole supply chain of the industry from system, integrated device manufacturer, foundry, assembly & test, to equipment and material companies. These include, Atotech S.E.A. Pte Ltd, Advanpack Solutions Pte Ltd, ASM Technology Singapore Pte Ltd, Disco Hi-Tec (S) Pte Ltd, Dow Corning Corporation, EV Group (EVG), GLOBALFOUNDRIES Singapore Pte Ltd, Heraeus Materials Singapore Pte Ltd, Hitachi Chemical Co., Ltd, Hisilicon Technologies Co. Ltd, Ibiden Singapore Pte Ltd, Infineon Technologies Asia Pacific Pte Ltd, OM Group Inc, Nissan Chemical Industries, Ltd, NEPES Pte Ltd, NXP Semiconductors, Optitune Pte. Ltd, Rolls-Royce Singapore, Shanghai Sinyang Semiconductor Materials Co. Ltd, Sekisui Chemical Co. Ltd, Silecs International Pte Ltd, Tokyo Ohka Kogyo Co. Ltd and UTAC, along with A*STAR Institute of High Performance Computing (IHPC) over the 18-month duration.

About Silecs International
Silecs develops and produces advanced polymers for use in semiconductor mask-making, fabrication and packaging, as well as in displays and solar applications. With major customers in Korea, Taiwan, Japan, Singapore, the US, and Europe, its state-of-the-art research and production capabilities have propelled it rapidly to the leading edge of microelectronics. It is headquartered in Singapore, with major offices also in Espoo, Finland.

For more information on Silecs, please visit http://www.silecs.com.

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